



Choosing the right soldering materials for your selective soldering process can be challenging!

Alpha just made the job much easier for you.



alpha

Selective Soldering Applications Are Increasing Industry-wide.

There has been a rapid increase in the use of selective soldering equipment for PCB assembly over the past several years. This is primarily due to the decrease in the number of through hole devices designed into boards along with the reduced equipment investment required. Because the selective soldering process is so much different than wave soldering, Alpha performed a comprehensive study designed to help our customers identify which of our leading liquid fluxes perform best under different selective soldering conditions. We also identified the specific condition where each flux performed at its best. Simply follow Steps 1 and 2 below to determine which ALPHA® flux best meets your process requirements.

Step 1

Using the following tables (below and top right), identify the conditions that most closely represent your selective soldering process and find the ALPHA® flux(es) that would fit your needs.

Note: Table 1 is for 1.6 mm (0.062") boards, and Table 2 is for 2.4mm (0.93") boards.

Settings required to achieve >75% fill on 100% of holes

Table 1 – 1.6mm Board

	FLUX	PROCESS GUIDELINES	FLUX	PROCESS GUIDELINES	FLUX	PROCESS GUIDELINES
5	EF2210	FS310, PH70	EF5601	FS190-250, PH70-130	EF2210	FS190, PH70-130
	EF6000	FS190-310, PH70-130	EF6000	FS190-310, PH70-130	EF5601	FS190-310, PH70-130
	EF6100	FS310, PH70	EF6100	FS190-310, PH70-130	EF6000	FS190-310, PH70-130
	EF6103	FS190-310, PH70-130	EF6103	FS190-310, PH70-130	EF6100	FS190-310, PH70-130
	EF8000	FS310, PH70-130	EF6850HF	FS310, PH70	EF6103	FS190-310, PH70-130
3.5			EF8000	FS310, PH70-130	EF6850HF	FS190-310, PH70-130
			EF9301	FS190, PH130, or; FS310, PH70	EF8000	FS190-310, PH70-130
	EF2210	FS310, PH70	EF2210	FS310, PH70	EF9301	FS190-310, PH70-130
	EF6000	FS310, PH70-130	EF6000	FS190-310, PH70-130	EF2210	FS190, PH130
	EF6103	FS310, PH70-130	EF6100	FS310, PH70-130	EF5601	FS190-250, PH110-130
2	EF8000	FS310, PH70	EF6103	FS190-310, PH70-130	EF6000	FS190-310, PH70-130
			EF8000	FS310, PH70-130	EF6100	FS190-310, PH70-130
	EF2210	FS310, PH70	EF2210	FS310, PH70	EF6103	FS190-250, PH100-130
	EF6000	FS310, PH70-130	EF6000	FS310, PH70-130	EF6850HF	FS190-310, PH70-130
	EF6103	FS310, PH70-130	EF6103	FS310, PH70-130	EF8000	FS190-310, PH70-130
				EF9301	FS310, PH70-100	
				EF6000	FS190-310, PH70-130	
				EF6100	FS190, PH130, or; FS310, PH70	
				EF6103	FS190, PH130	
				EF6850HF	FS190, PH70-130	
				EF8000	FS310, PH70	

LEGEND
 FS = Flux Solids, µg/cm²
 PH = Pre-Heat, °C
 Green Numbers = Optimum Settings

Solder Pot Temperature, °C

These are general guidelines which have proven to yield excellent results; however, depending upon your equipment, components, and circuit boards, your optimal settings may be different.

Settings required to achieve >75% fill on 100% of holes

Table 2 – 2.4mm Board

	FLUX	PROCESS GUIDELINES	FLUX	PROCESS GUIDELINES	FLUX	PROCESS GUIDELINES	
Solder Contact Time, seconds	5	EF6000	FS190, PH130	EF6000	FS190-290, PH100-130	EF2210	FS190, PH70
		EF6103	FS310, PH130	EF6100	FS190, PH130	EF6000	FS190-310, PH70-130
		EF8000	FS310, PH70	EF6103	FS190-310, PH100-130	EF6100	FS190-310, PH70-130
	3.5	N/A		EF6000	FS190, PH130	EF6000	FS190-310, PH70-130
		N/A		EF6103	FS190, PH130	EF6100	FS190-310, PH70-130
		N/A				EF6103	FS190, PH100-130
	2	N/A		N/A		EF6850HF	FS190-310, PH70-100
		N/A		N/A		EF8000	FS310, PH70
		N/A		N/A		EF6000	FS190-250, PH130
N/A		N/A		EF6100	FS190-250, PH130		
N/A		N/A		EF6103	FS190, PH130		
N/A		N/A		EF6850HF	FS190, PH70		
280		295		310			

LEGEND

- FS = Flux Solids, µg/cm²
- PH = Pre-Heat, °C
- Green Numbers = Optimum Settings

Solder Pot Temperature, °C

These are general guidelines which have proven to yield excellent results; however, depending upon your equipment, components, and circuit boards, your optimal settings may be different.

Step 2

Use the table below to further qualify the right ALPHA[®] flux for your application based on the flux's electrochemical reliability.

Note: Additional information about each flux can be found at alpha.alent.com.

Reliability Requirements

TYPE	DESCRIPTION	IPC SIR (004A)	BELLCORE SIR	IPC SIR (004B)	JIS / CUSTOM
I	Simple, single sided, FR2 / CEM-1 laminates				EF-12000
II	Dual sided FR-4 w/PTHs, 1.6mm thick, up to 4 inner copper layers, metallized pad finishes				EF-9301(10)
III	Complex, up to 12 inner copper layers, OSP pad finishes, all processing in air	EF-6000	EF-2210	EF-6100(P)	EF-6103
					EF-6850HF
IV	>2.4mm thick, >12 inner copper layers, large high heat capacity components		EF-8300(LR)		EF-8000(GL)

Alcohol Based

Water Based

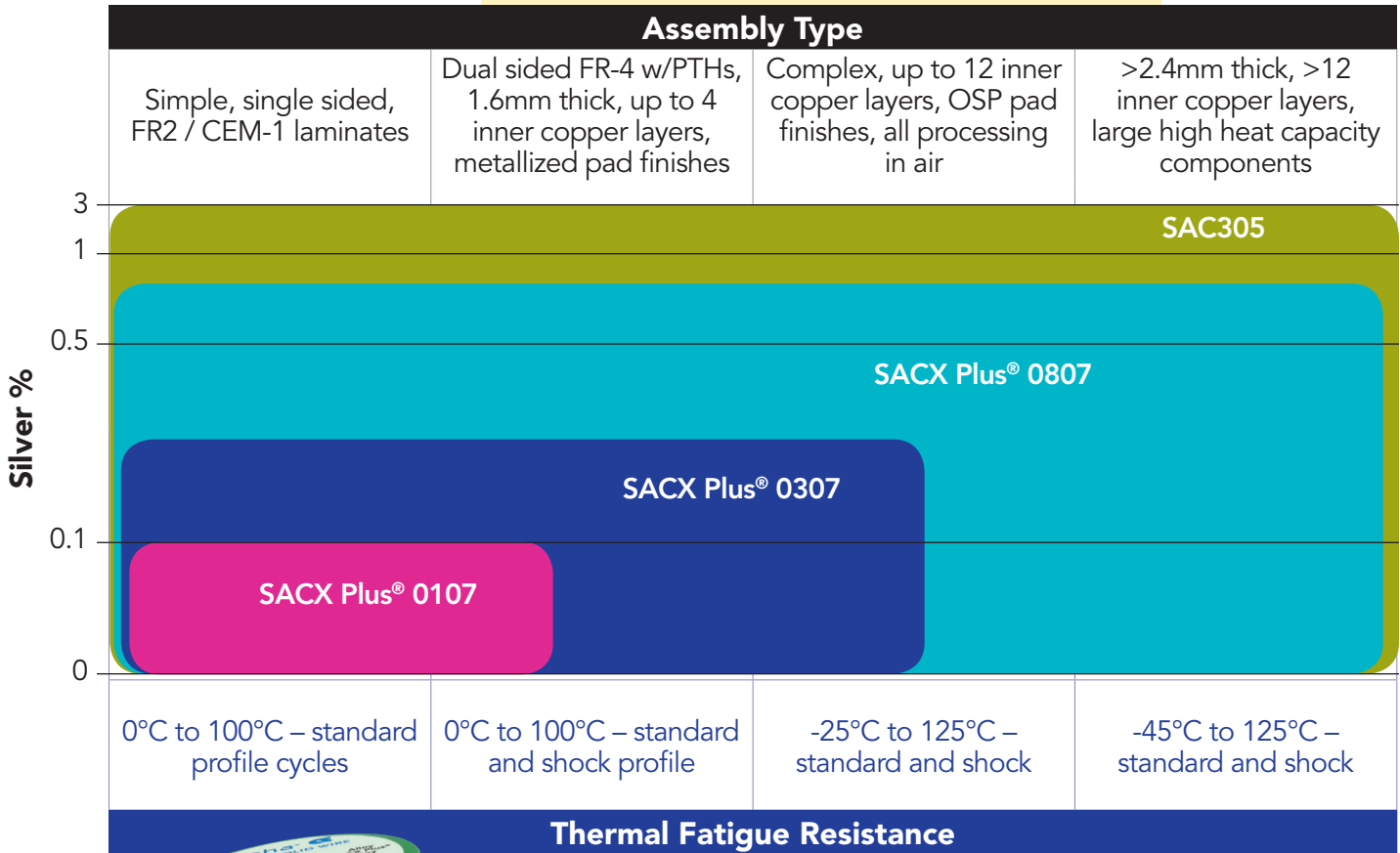
ALPHA® SACX Plus® Alloys

ALPHA® SACX Plus® alloys are ideal for use in selective soldering applications. They are engineered to provide excellent solderability with minimal dross, and they also resist copper dissolution in processes requiring long, high temperature contact times.

Select the right ALPHA® SACX Plus® alloy for your board type using the chart below. You should also consider your mechanical reliability requirements.



Technology Enabling Alloys



All our ALPHA® SACX Plus® alloys are available in a wide variety of diameters in solid wire form for use as a replenishment alloy in most selective soldering machines.

www.alpha.alent.com

Worldwide/Americas Headquarters
109 Corporate Boulevard
South Plainfield, NJ 07080
USA
+1-814-946-1611 – Dial 0

European Headquarters
Forsyth Road
Sheerwater
Woking GU215RZ
United Kingdom
+44-1483-758-400

Asia-Pacific Headquarters
8/F, Paul Y. Centre
51 Hung To Road
Kwun Tong
Kowloon, Hong Kong
+852-3190-3100

SM1157
©2013 Alpha

alpha®